



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	TCOT*F715S6C	A	Z6TA	2016-02-23
Amount	UoM	Unit type	ST ECOPACK Grade	
640.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	1.7X1.5X0.140	8	No lead	
Comment	Package: DFN.17.15.06-040-8L-E, MD valid for CP:BD135, BD135-16, BD139,BD139-16.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

640.000

Material Composition Declaration						Mfr Item Name	TCOT*F71556C		640.0000			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.772	mg	supplier	die	Silicon (Si)	7440-21-3		0.744	mg	963255	1147
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	11811	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	14436	17
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	1312	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	2625	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	6562	8
Leadframe	Copper & its alloys	359.022	mg	supplier	alloy	Copper (Cu)	7440-50-8		283.627	mg	789999	443173
				supplier	alloy	Iron (Fe)	7439-89-6		53.854	mg	150003	84148
				supplier	alloy	Phosphorous (P)	12185-10-3		14.360	mg	39997	22438
				supplier	alloy	Nickel (Ni)	7440-02-0		7.181	mg	20001	11220
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	3.730	mg	958869	5828
Soft solder	Solder	3.890	mg	JIG - R	solder	Tin (Sn)	7440-31-5		0.070	mg	17995	109
				JIG - R	solder	Silver (Au)	7440-22-4		0.090	mg	23136	141
				JIG - R	solder	Copper (Cu)	7440-50-8		0.401	mg	1000000	627
Bonding wires mg	Other inorganic materials	0.401	mg	supplier	wire	Copper (Cu)	7440-50-8		0.401	mg	1000000	627
				supplier	mold compound	Silica (SiO2)	60676-86-0		256.409	mg	1000000	400645
				supplier	mold compound	Antimony Oxide	1309-64-4		13.639	mg	833323	21311
				supplier	mold compound	Carbon Black	1333-86-4		2.728	mg	166677	4263
Connections coating	Solder	3.139	mg	supplier	alloy	Tin (Sn)	7440-31-5		3.139	mg	1000000	4905